

CLAIMS

1. A device for bonding chips (7) onto a semiconductor substrate (11') or further chips,
wherein the chips (7) can be bonded onto the semiconductor substrate (11') or the further chips by means of a direct bond, and
wherein a bond head (9) bonds the chips (7) onto the semiconductor substrate (11') or the further chips such that the chips (7) are bonded at first in the center and then to the outside.
2. The device according to claim 1, having an ejector device (1) with depressions (2) for positioning and/or fixing the chips (7).
3. The device according to claim 2, wherein lead-throughs (3), in particular holes, are located on bottom surfaces of the depressions (2), wherein a lifting device (4) can lift the chips (7) through the lead-throughs (3) to make the chips (7) accessible for a gripper (5).
4. The device according to claim 2, wherein a depth (t) of the depressions (2) corresponds to a height of the chips (7).
5. The device according to claim 3, wherein the gripper (5) fixes the chip (7) on the fixing surface (22) located opposite to a bond surface (7b).
6. The device according to claim 2, having a mask (23) with an aperture (24), wherein the mask (23) can be moved across the ejector device (1, 1'), which is located with the chips (7), until the aperture (24) is located above the chip (7), which is to be bonded next.
7. The device according to any one of the preceding claims, the bond head (9) for fixing, transporting and bonding the chips (7).